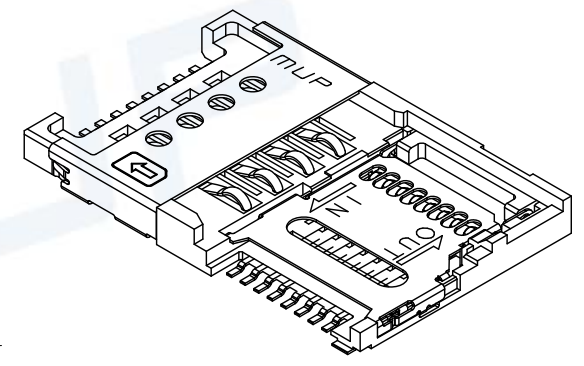
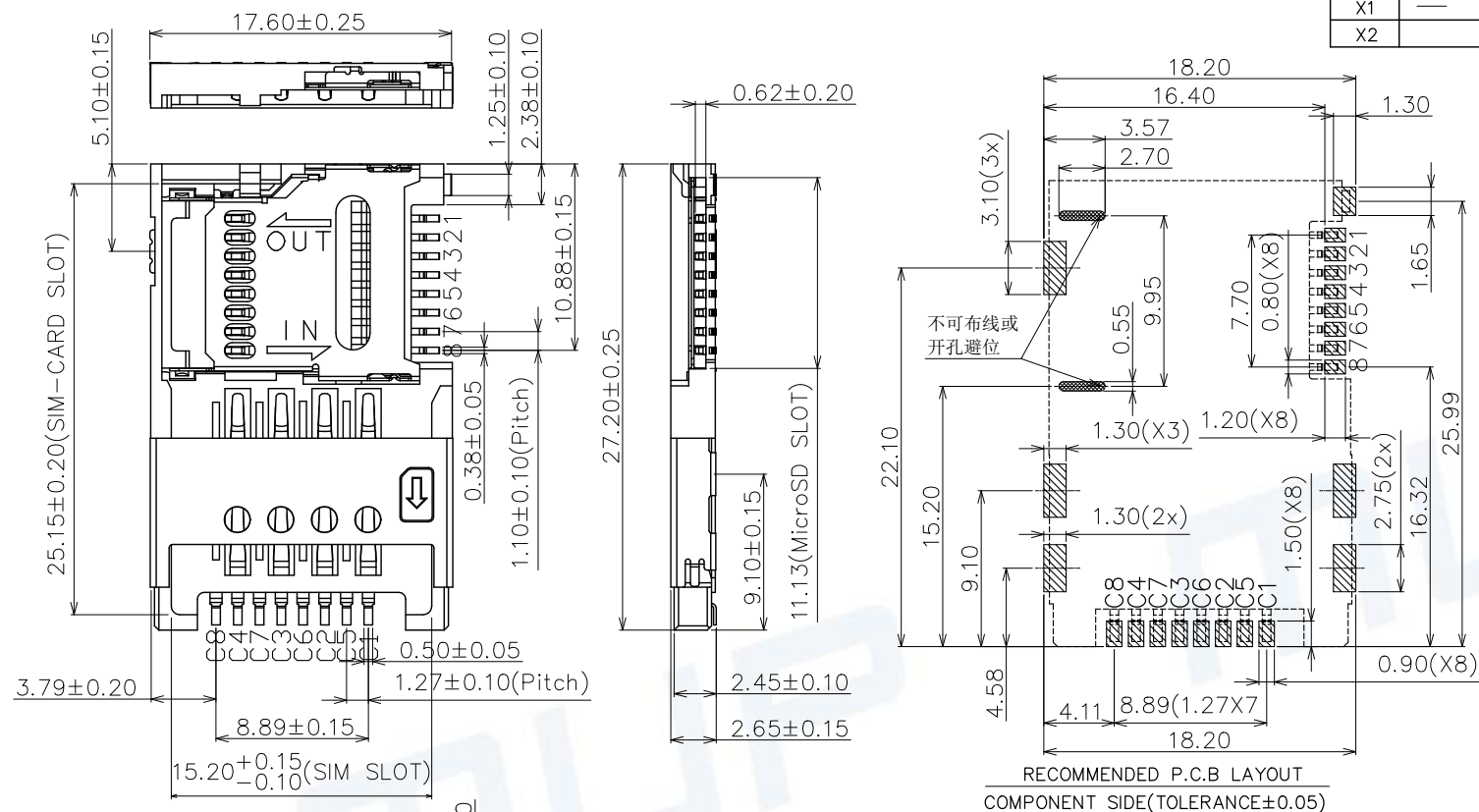


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	—	—	—	—	—
X2	—	—	—	—	—



TECHNICAL CHARACTERISTICS

1.General Characteristics
 Dimensions: 27.20LX17.68WX2.65H mm
 Weight: Approx1.22±0.2g
 Durability: 5,000 cycles min.

2.Electrical Characteristics
 Contact resistance: 50mΩ typical,100mΩ max
 Insulation resistance: >1000MΩ/500V DC

3.Solderability
 Vapor phase: 215°C,30sec.Max
 IR reflow: 260°C,10sec.Max
 Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics
 Operating temperature: -40°C~+85°C
 Operating humidity: 10%~+95%RH

Micro SD CARD		SIM CARD	
Pin No.	NAME	Pin No.	NAME
1	DAT2	C1	VCC
2	CD/DAT3	C2	RST
3	CMD	C3	CLK
4	VDD	C4	Reserved
5	CLK	C5	GND
6	VSS	C6	VPP
7	DAT0	C7	I/O
8	DAT1	C8	Reserved

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	SIM TERMINAL	8	Copper Alloy	Contact area:5μ Au plated Solder tail:G/F Au plated Under plated:50μ Ni plated
3	SIM SHELL	1	Stainless Steel	Contact area:5μ Au plated Under plated:50μ Ni plated
4	Micro SD TERMINAL	8	Copper Alloy	Contact area:5μ Au plated Solder tail:G/F Au plated Under plated:50μ Ni plated
5	HOLDER	1	Copper Alloy	Solder tail:G/F Au plated Under plated:50μ Ni plated
6	Micro SD SHELL	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **2 in 1 Card Connector**

MODEL NO: **MUP M619-2**

TYPE: **Micro SD8pin+SIM8pin**

PROJ.	UNIT	SCALE	DRAWN	huabo Dec.11.2021	DWG NO.:
①	MM	1:1	CHECKED	Zoey Dec.11.2021	DWG-MUP-M619-002
CUSTOMER DRAWING			APPROVAL	Simon Dec.11.2021	SHEET
					1/1
					REVISION
					X1

